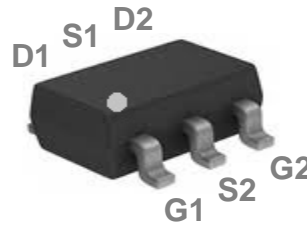
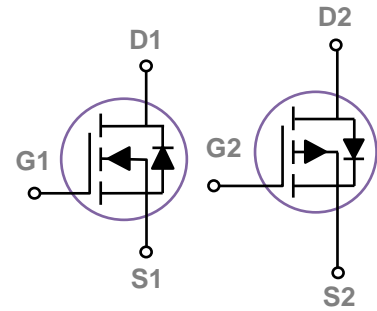


### Main Product Characteristics

Polarity	N-Ch	P-Ch
$V_{DSS}$	20V	-20V
$R_{DSon(max.)}$	40mΩ	100mΩ
$I_D$	3.8A	-2.5A



SOT-23-6L



Schematic Diagram

### Features and Benefits

- Advanced MOSFET process technology
- Ideal for DC-DC converter, power management in portable battery, computer, printer, cellular and general purpose applications
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



### Description

The SSF2116 utilizes the latest processing techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in DC-DC converter, power management in portable battery, computer, printer, cellular and general purpose applications.

### Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	N-Channel	P-Channel	Unit
$V_{DS}$	Drain-Source Voltage	20	-20	V
$V_{GS}$	Gate-Source Voltage	$\pm 10$	$\pm 10$	V
$I_D$	Drain Current – Continuous ( $T_C=25^\circ\text{C}$ )	3.8	-2.5	A
	Drain Current – Continuous ( $T_C=100^\circ\text{C}$ )	2.3	-1.5	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	15.2	-10	A
$P_D$	Power Dissipation ( $T_C=25^\circ\text{C}$ )	1.25	1.25	W
	Power Dissipation – Derate above $25^\circ\text{C}$	0.01	0.01	W/ $^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150		$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150		$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	100	$^\circ\text{C}/\text{W}$

### N-Channel Electrical Characteristics

( $T_J=25^\circ\text{C}$  unless otherwise specified)

#### Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	20	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.02	---	$V/^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=20V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	$\mu A$
		$V_{DS}=16V, V_{GS}=0V, T_J=125^\circ\text{C}$	---	---	10	$\mu A$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 10V, V_{DS}=0V$	---	---	$\pm 100$	nA

#### On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=4.5V, I_D=3A$	---	30	40	$m\Omega$
		$V_{GS}=2.5V, I_D=2A$	---	42	55	$m\Omega$
		$V_{GS}=1.8V, I_D=1.5A$	---	55	70	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	0.3	0.6	1	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-2	---	$mV/^\circ\text{C}$
gfs	Forward Transconductance	$V_{DS}=10V, I_D=2A$	---	4.4	---	S

#### Dynamic and Switching Characteristics

$Q_g$	Total Gate Charge <sup>2,3</sup>	$V_{DS}=10V, V_{GS}=4.5V, I_D=3A$	---	5.8	10	nC
$Q_{gs}$	Gate-Source Charge <sup>2,3</sup>		---	0.6	1.5	
$Q_{gd}$	Gate-Drain Charge <sup>2,3</sup>		---	1.5	3	
$T_{d(on)}$	Turn-On Delay Time <sup>2,3</sup>	$V_{DD}=10V, V_{GS}=4.5V, R_G=25\Omega$ $I_D=1A$	---	2.9	6	ns
$T_r$	Rise Time <sup>2,3</sup>		---	8.4	16	
$T_{d(off)}$	Turn-Off Delay Time <sup>2,3</sup>		---	19.2	38	
$T_f$	Fall Time <sup>2,3</sup>		---	5.6	12	
$C_{iss}$	Input Capacitance	$V_{DS}=15V, V_{GS}=0V, F=1\text{MHz}$	---	315	600	pF
$C_{oss}$	Output Capacitance		---	50	80	
$C_{riss}$	Reverse Transfer Capacitance		---	40	60	

#### Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V$ , Force Current	---	---	3.8	A
$I_{SM}$	Pulsed Source Current		---	---	7.6	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

### P-Channel Electrical Characteristics

( $T_J=25^\circ\text{C}$  unless otherwise specified)

#### Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-20	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to 25, $I_D=-1mA$	---	-0.01	---	$V/^\circ C$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=-20V, V_{GS}=0V, T_J=25^\circ C$	---	---	-1	$\mu A$
		$V_{DS}=-16V, V_{GS}=0V, T_J=125^\circ C$	---	---	-10	$\mu A$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 10V, V_{DS}=0V$	---	---	$\pm 100$	nA

#### On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=-4.5V, I_D=-3A$	---	82	100	$m\Omega$
		$V_{GS}=-2.5V, I_D=-2A$	---	125	140	$m\Omega$
		$V_{GS}=-1.8V, I_D=-1A$	---	197	230	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=-250\mu A$	-0.3	-0.6	-1.0	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	3	---	$mV/^\circ C$
gfs	Forward Transconductance	$V_{DS}=-10V, I_D=-1A$	---	2.2	---	S

#### Dynamic and switching Characteristics

$Q_g$	Total Gate Charge <sup>2,3</sup>	$V_{DS}=-10V, V_{GS}=-4.5V, I_D=-2A$	---	4.8	10	nC
$Q_{gs}$	Gate-Source Charge <sup>2,3</sup>		---	0.5	1	
$Q_{gd}$	Gate-Drain Charge <sup>2,3</sup>		---	1.9	4	
$T_{d(on)}$	Turn-On Delay Time <sup>2,3</sup>	$V_{DD}=-10V, V_{GS}=-4.5V, R_G=25\Omega$ $I_D=-1A$	---	3.5	7	ns
$T_r$	Rise Time <sup>2,3</sup>		---	12.6	24	
$T_{d(off)}$	Turn-Off Delay Time <sup>2,3</sup>		---	32.6	62	
$T_f$	Fall Time <sup>2,3</sup>		---	8.4	16	
$C_{iss}$	Input Capacitance	$V_{DS}=-15V, V_{GS}=0V, F=1MHz$	---	350	510	pF
$C_{oss}$	Output Capacitance		---	65	95	
$C_{rss}$	Reverse Transfer Capacitance		---	50	75	

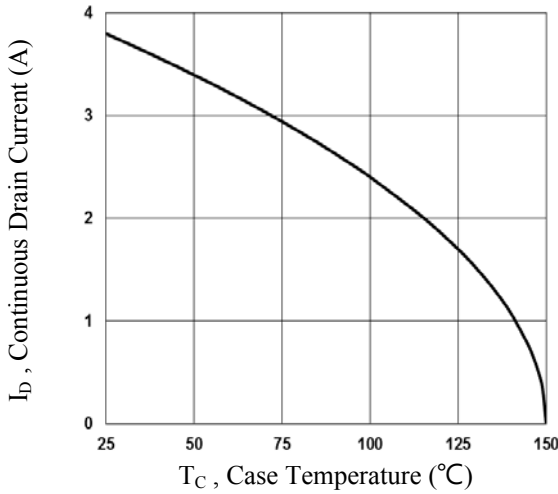
#### Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V, \text{Force Current}$	---	---	-2.5	A
$I_{SM}$	Pulsed Source Current		---	---	-5	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V, I_S=-1A, T_J=25^\circ C$	---	---	-1	V

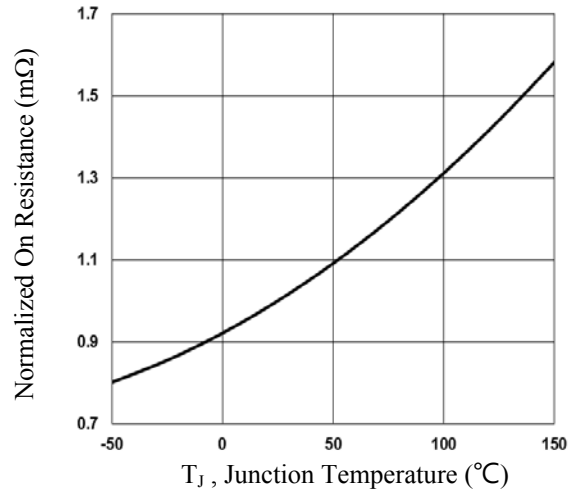
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

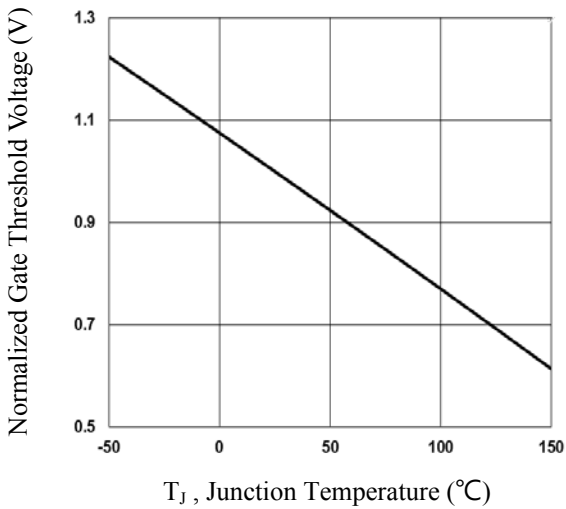
**Typical Characteristic Curves-N-Channel**



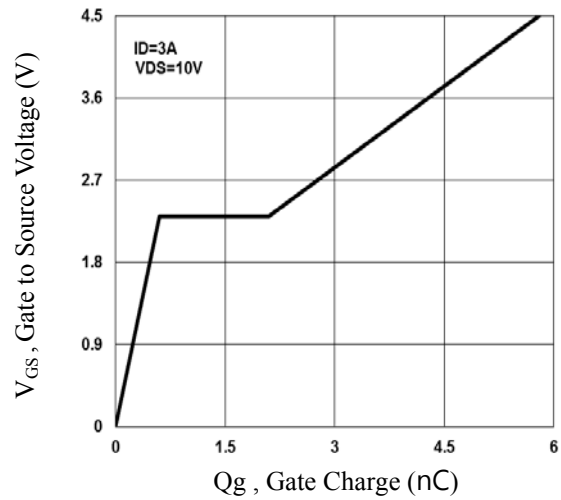
**Fig.1 Continuous Drain Current vs.  $T_c$**



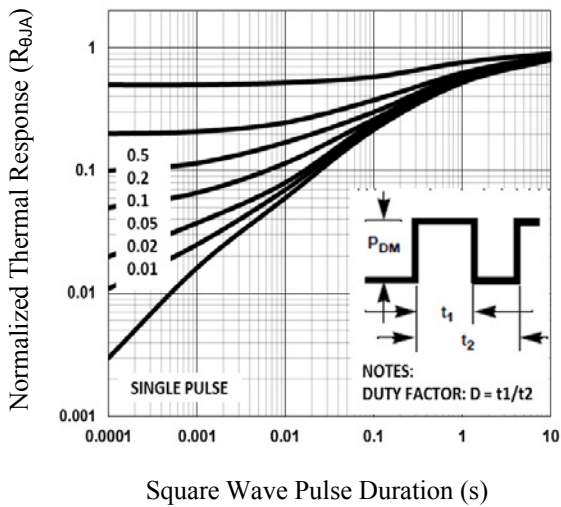
**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_j$**



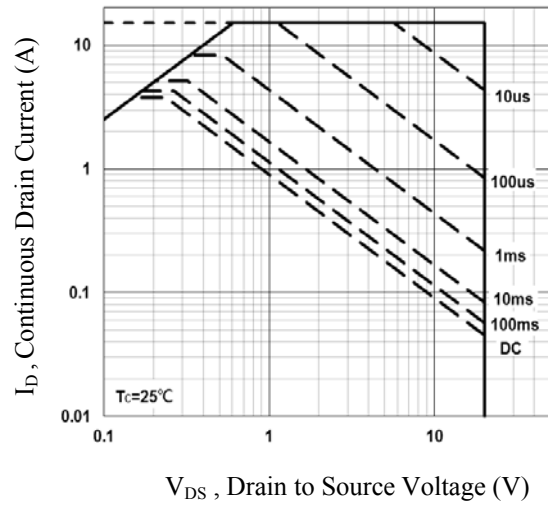
**Fig.3 Normalized  $V_{th}$  vs.  $T_j$**



**Fig.4 Gate Charge Waveform**

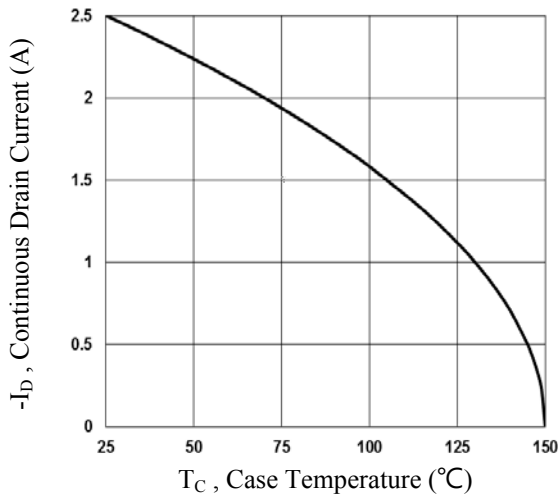


**Fig.5 Normalized Transient Impedance**

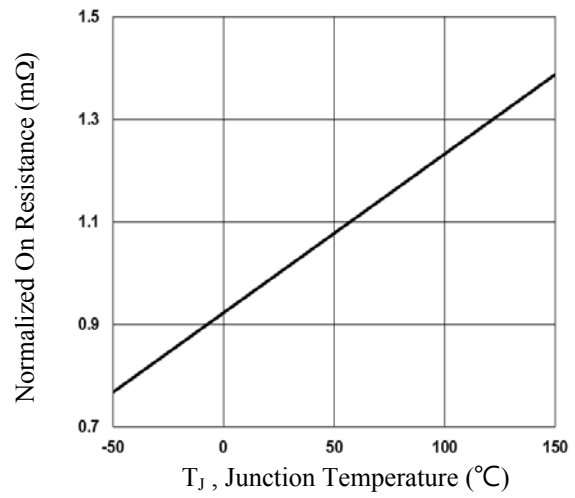


**Fig.6 Maximum Safe Operation Area**

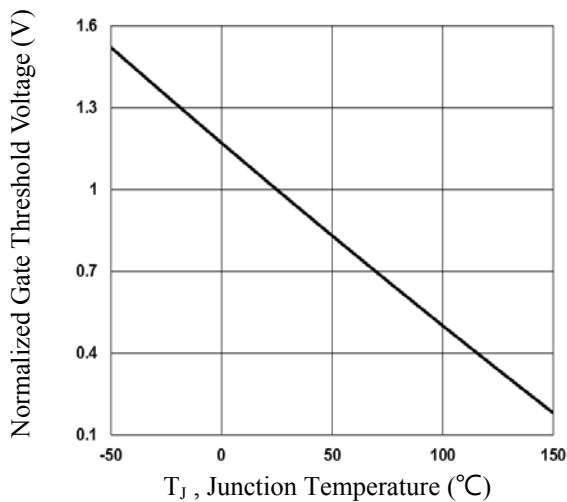
**Typical Characteristic Curves-P-Channel**



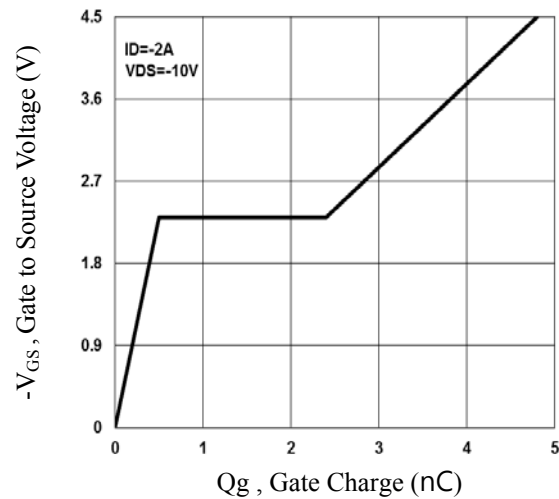
**Fig.7 Continuous Drain Current vs.  $T_C$**



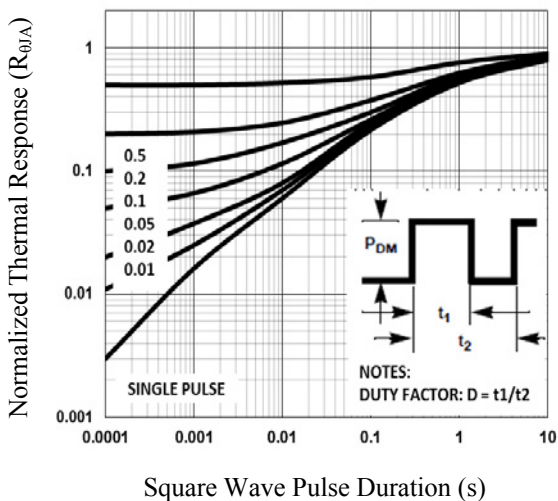
**Fig.8 Normalized  $R_{DS(on)}$  vs.  $T_J$**



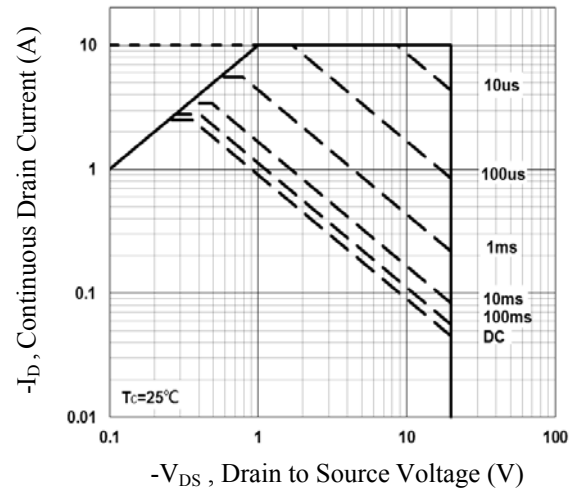
**Fig.9 Normalized  $V_{th}$  vs.  $T_J$**



**Fig.10 Gate Charge Waveform**



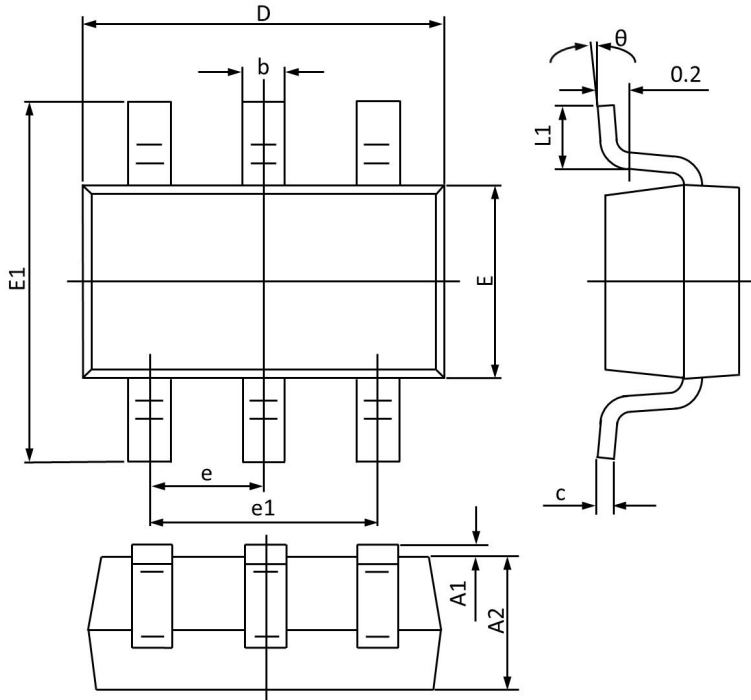
**Fig.11 Normalized Transient Impedance**



**Fig.12 Maximum Safe Operation Area**

## Package Outline Dimensions

## SOT-23-6L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A1	0.000	0.100	0.000	0.004
A2	1.000	1.200	0.040	0.047
b	0.300	0.500	0.012	0.019
c	0.047	0.207	0.002	0.008
D	2.800	3.000	0.110	0.118
E	1.500	1.800	0.059	0.070
E1	2.600	3.000	0.103	0.118
e	0.950 TYP		0.037 TYP	
e1	1.900 TYP		0.075 TYP	
L1	0.250	0.550	0.010	0.021
θ	0°	8°	0°	8°